10 LAYER STACK UP AS IN ALLEGRO FOR 50 OHM,90 OHM, 100 OHM and 120 OHM

			TRACE WIDTH/SPACING	TRACE WIDTH/SPACING		TRACE WIDTH/SPACING	
SL NO	**LAYER NAME**	**THICKNESS(MILS)**	**50 OHM SINGLE ENDED**	**100 OHM DIFFRENTIAL**	**IMPEDANCE**	**120 OHM DIFFRENTIAL**	**IMPEDANCE**
1	L1_TOP SIDE	1.909	6.5	5/6.8 MILS	99.972	5/16.5	109.72
	PREPREG 1	4					
2	L2 PWR PLN1	1.378					
	CORE 1	6					
3	L3_SIG_1	1.378	5.9	5/13 MILS	99.929	5/22.9	105.14
	PREPEG 2	8					
4	L4_SIG_2	1.378	5.9	5/13 MILS	99.929	5/22.9	105.14
	CORE 2	6					
5	L5_GND PLN 1	1.378	5.9				
	PREPREG 3	4					
6	L6_PWR PLN2	1.378					
	CORE 3	6					
7	L7_SIG_3	1.378	5.9	5/13 MILS	99.929	5/22.9	105.14
	PREPREG 3	8					
8	L8_SIG_4	1.378	5.9	5/13 MILS	99.929	5/22.9	105.14
	CORE 4	6					
9	L9_GND PLN2	1.378					
	PREPREG 4	4					
10	L10_BOTTOM_SIDE	1.909	6.5	5/6.8 MILS	99.972	5/16.4	109.69

TOTAL	**66.842**

BOARD CHARACTERISTICS

		Value	Remarks
1	**Layers**	10	
2	**Impedance Matching**	Yes	50 OHMS SINGLE AND 100,120 OHM DIFFRENTIAL
3	**Minimum Drill/Pad**	8/18 Mils	
4	**Copper Thickness**	35 Micron	TOP & BOTTOM 52.2 Micron
5	**Minimum Annular ring**	3 mils	For BGA Parts
6	**Assembly**	Double Sided	